

are directed to a structure, the title should be changed to indicate the structure and not the method. It is Applicant's belief that the invention, as well as the claims, are directed towards both a structure and a method of manufacturing that structure. Therefore Applicant hereby amends this application by substituting the following title: "Multi-Layer Circuit Board and Method of Manufacture".

III. Summary Of Claim Status

The patent prosecution history on this application has been complex and unconventional. Applicant is hopeful that this Response will help to clear up the confusions and misunderstandings that have plagued the prosecution to date. The present Responses to the Office Actions mailed 05/02/06 and 08/07/06 cancel all of the previous claims, and submits amended claims. Further, as pointed out in the following Remarks section, the Applicant respectfully believes that the prior art cited by the Examiner is distinguishable from the present invention in that the cited references fail to disclose significant novel elements of the Applicant's invention.

The current status of the application's claims:

Claims 1-4, 7, 13, and 17 are pending, but were rejected in the 08/07/06 Office Action.

Claims 1-4, 7, 13, and 17 are hereby withdrawn.

Amended claims 18-31 are hereby submitted for consideration by the Examiner.